SENSING THE BEAUTIFUL LIFE

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MEMSIC

MEMSIC Semiconductor is a world-leading IC product company, mainly engaged in MEMS sensor R&D, manufacturing and sales, providing "one-stop" sensor solutions of MEMS sensor chip, software algorithm and applications. MEMSIC now realizes large-scale production of world's most exclusive thermal accelerometer, AMR geomagnetic sensor, capacitive accelerometer, and micropower Hall Switch, that are widely applied to different fields such as automobile, industrial, medical, wearable, smart home, and consumer electronics.

AMR 3D Magnetometer

- **Ultra-Small**
- **Low Noise**
- **High Sensitivity**
- **High Accuracy**

History of MEMSIC Magnetometers | Mobile & Tablets | Automotive Infotainment | Drone

MMC5633NJL
MMC5616WA
- Monolithic integrated 3-axis magnetometers
- Advanced AMR technology
- Wafer level package size: 0.8×0.8×0.4mm
- MMC5633NJL fully supports I3C interfaces

MMC3630KJ
- Mature process, stable and reliable performance
- Low noise, strong anti-interference ability
- Package size: 1.2×1.2×0.5mm

MMC5983MA
MMC3416xPJ
- Low temperature drift, low noise, low hysteresis, high accuracy
- High reliability, good stability, strong anti-interference ability
- MMC5983MA is AEC-Q100 Grade 2 certified
- MMC3416xPJ has ultra-low power consumption, support up to 8 I²C addresses

Hall Switch

- **Ultra-Low Power**
- **Ultra Small Package Size Multiple Package Types**
- **Ultra-Wide Operation Voltage Range**
- **Accurate Switch Control Multiple Package Types**

MHA100KN
- Omni polar and dual output, ultra-low power consumption, high sensitivity
- Package size: DFN 4 1.0×1.4×0.37mm

MHA150N/S
- Unipolar and single output, ultra-low power consumption, high sensitivity
- Package size: SOT23-3L 2.9×1.6×1.1mm

MHA160N/S
- Unipolar and single output, ultra-low power consumption, high sensitivity
- Package size: SOT23-3L 2.9×1.2×0.55mm

MHA183AS
- Unipolar and single output, ultra-low power consumption, high sensitivity
- Package size: SOT23-3L 2.9×1.2×1.1mm

Capacitive Accelerometer & 6-Axis IMU

- **Low Power Consumption**
- **Ultra Small Package Size**
- **Multiple Functions & Algorithm Support**

MC3416
- 16-bit high resolution, support I²C communication mode
- Low noise, low offset, low temperature drift
- Package size: LGA-12 2×2×0.95mm

MC3419
MC3479
- 16-bit high resolution, support I²C/SPI communication mode, with FIFO cache
- Low noise, low offset, low temperature drift
- Package size: LGA-12 2×2×0.95mm

MC3630
MC3632
MC3635
- 14-bit resolution, support I²C/SPI communication mode, with FIFO cache
- Ultra-low power consumption, supports a variety of low-power modes
- Package size: LGA-12 2×2×0.95mm
- MC3635 Package size: LGA-10 1.6×1.6×0.94mm

MC3672
- 14-bit resolution, support I²C/SPI communication mode, with FIFO cache
- Ultra-small size, ultra-low power consumption, support a variety of low power modes
- Package size: CSP-8 1.29×1.08×0.74mm

MXC3500AL
- 16-bit resolution, support I²C/SPI communication mode
- 1.5KB ultra-large FIFO cache, multiple low power modes
- Single/double/triple tap break, step counter
- Package size: LGA-12 2×2×0.73mm

MIC61XX
- 16-bit high resolution, 3KB FIFO, support I²C/I3C/SPI communication mode, up to 2200Hz ODR
- Gyro 0-rate offset +/-3%, offset over temperature +/-0.05dps/C, sensitivity error +/-1%
- Package size: LGA 2.5×3×0.83mm

NEW

Thermal Accelerometer

- **Monolithic Integration**
- **Extremely Impact resistant**
- **Ultra-Small Size**
- **Ultra-Low Temperaturedrift**

MXC4005XC
MXC6655XA
- 3-axis monolithic integration, wafer level package, ultra-small size, stable performance, low failure rate
- Used in consumer electronic devices such as mobile phones and tablets
- MXC4005XC Package size: 1.2×1.7×0.95mm
- MMC5566XA Package size: 2×2×1mm

MXR7150VW
MXR7999VW
- 2-axis monolithic integration, the temperature compensations for the offset and sensitivity are done respectively, can be mounted flat or vertically, flexible installation
- Analog output, MXR7999VW has +/- 2g range and 1000mV/g sensitivity
- MXR7150VW has +/- 13.3g range and 150mV/g sensitivity
- AEC-Q100 Grade 1 certified, widely used in active suspension, ESC and EPB systems
- Package size: 5.5×5.5×2.7mm

MXD2020EL
MXD6235Q
- 2-axis, PWM digital output
- Good consistency of offset and sensitivity, easy for temperature compensations
- MXD2020EL has +/- 1g range and 0.2mg/ SQRT (Hz) noise
- MXD6235Q has +/- 1.5g range and 0.13mg/ SQRT (Hz) noise
- Used in level gauge, home appliance and other industrial applications
- Package size: 5.5×5.5×2mm

MXR7205VW
- 2-axis, the temperature compensations for the offset and sensitivity are done respectively, can be mounted flat or vertically, flexible installation.
- SPI digital output, range +/- 5G, sensitivity 800LSB/g
- AEC-Q100 Grade 2 certified, used in automotive ESC and EPB systems.
- Package size: 5.5×5.5×2.7mm